

## Product Change Notification / CENO-23PKZQ392

| D | a | t | Δ | • |
|---|---|---|---|---|
| u | а | L | ㄷ |   |

14-Feb-2023

## **Product Category:**

**Ethernet PHYs** 

## **PCN Type:**

Manufacturing Change

# **Notification Subject:**

CCB 6062 Initial Notice: Qualification of EN4900G as a new die attach material for KSZ8041TL, SPNY801037, KSZ8041FTLI, KSZ8041TL-TR, SPNZ801037-TR, and KSZ8041FTLI-TR catalog part numbers (CPN) available in 48L TQFP (7x7x1.0mm) package.

### **Affected CPNs:**

CENO-23PKZQ392\_Affected\_CPN\_02142023.pdf CENO-23PKZQ392\_Affected\_CPN\_02142023.csv

#### **Notification Text:**

PCN Status:Initial Notification

PCN Type:Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of EN4900G as a new die attach material for KSZ8041TL, SPNY801037, KSZ8041FTLI, KSZ8041TL-TR, SPNZ801037-TR, and KSZ8041FTLI-TR catalog part numbers (CPN) available in 48L TQFP (7x7x1.0mm) package.

## **Pre and Post Change Summary:**

|                              |             | Pre Cl          | hange                       | Post Change                                       |  |  |  |
|------------------------------|-------------|-----------------|-----------------------------|---------------------------------------------------|--|--|--|
| Assembly Site                |             |                 | niconductor<br>s, Ltd (OSE) | Orient<br>Semiconductor<br>Electronics, Ltd (OSE) |  |  |  |
| Wire Material                |             | А               | .U                          | Au                                                |  |  |  |
| Die Attach Material          |             | 83              | 40                          | EN4900G                                           |  |  |  |
| Molding Compound<br>Material |             | CEL-92          | 200HF                       | CEL-9200HF                                        |  |  |  |
|                              | Material    | C7025           |                             | C7025                                             |  |  |  |
| Lead-Frame                   | Paddle Size | 120x120<br>mils | 160x160<br>mils             | 120x120 mils                                      |  |  |  |

#### Impacts to Data Sheet:None

Change ImpactNone

**Reason for Change:**To improve manufacturability by qualifying EN4900G as a new Die attach material.

**Change Implementation Status:**In Progress

## **Estimated Qualification Completion Date:**May 2023

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

## Time Table Summary:

|                             | January 2022 |   |   |   | > | May 2023 |     |        |   |   |   |
|-----------------------------|--------------|---|---|---|---|----------|-----|--------|---|---|---|
| Workweek                    | 1            | 2 | 3 | 4 | 5 |          | 1 8 | 1<br>9 | 2 | 2 | 2 |
| Initial PCN Issue<br>Date   |              |   |   | Х |   |          |     |        |   |   |   |
| Qual Report<br>Availability |              |   |   |   |   |          |     |        |   | Х |   |
| Final PCN Issue             |              |   |   |   |   |          |     |        |   | Х |   |

| _      | _ | _ |   | _ | _ | _ |   | _ | _ | _ |   |
|--------|---|---|---|---|---|---|---|---|---|---|---|
| l      |   |   |   |   |   |   | 1 |   |   |   | ı |
| l Date |   |   |   |   |   |   |   |   |   |   | ı |
| Date   | l |   | l |   |   |   | l |   |   |   | L |

Method to Identify Change: Traceability code

**Qualification Plan:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:** January 27, 2023: Issued initial notification.

February 14, 2023: Re-issued initial notification. Update the Pre and Post Change Summary to include Lead Frame Paddle size and attached Pre and Post Change Summary.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

#### Attachments:

PCN\_CENO-23PKZQ392\_Pre and Post Change\_Summary.pdf PCN\_CENO-23PKZQ392\_Qual Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

#### **Terms and Conditions:**

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

CENO-23PKZQ392 - CCB 6062 Initial Notice: Qualification of EN4900G as a new die attach material for KSZ8041TL, SPNY801037, KSZ8041FTLI, KSZ8041TL-TR, SPNZ801037-TR, and KSZ8041FTLI-TR catalog part numbers (CPN) available in 48L TQFP (7x7x1.0mm) package.

Affected Catalog Part Numbers (CPN)

KSZ8041TL

SPNY801037

KSZ8041FTLI

KSZ8041TL-TR

SPNZ801037-TR

KSZ8041FTLI-TR

Date: Tuesday, February 14, 2023